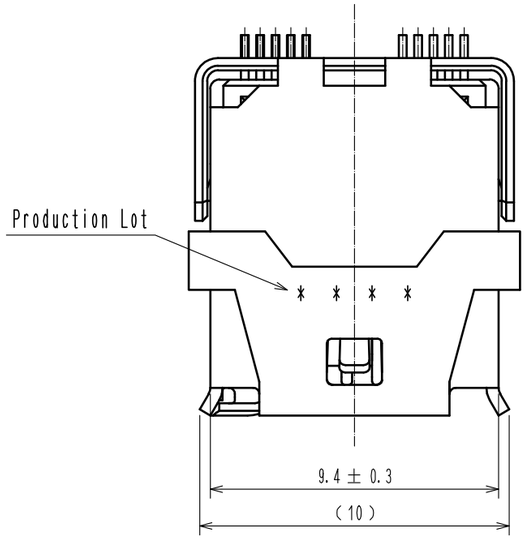
2019/06/17 17:56:04 TS.SAKAIZAWA



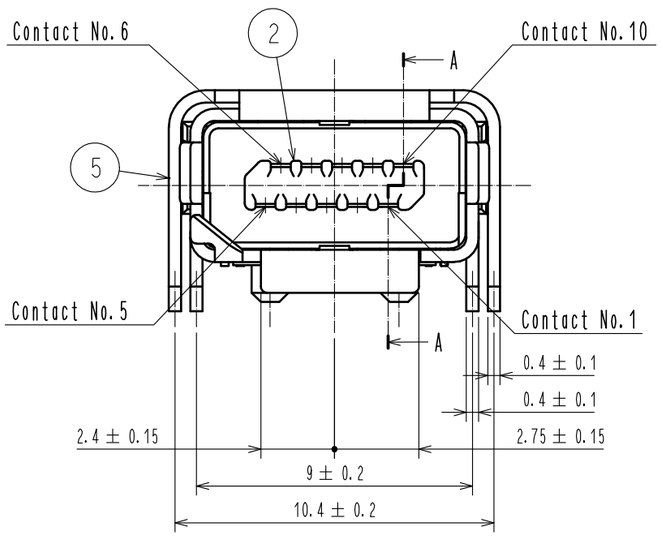
Notes. 1 Co-planarity is within 0.1 mm.

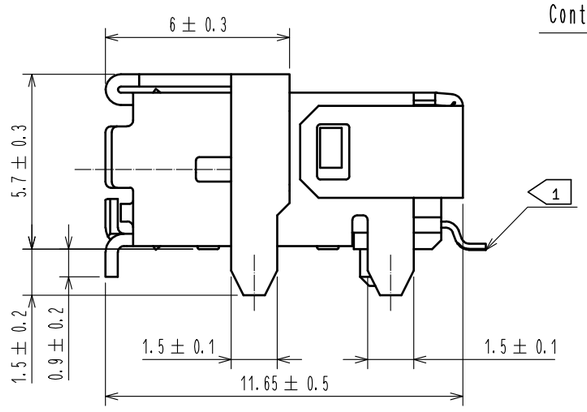
2. As for part No.5 the performance remains good even if there are rubbing wounds by the assembly process.
And the perfomance remains good though there might be a difference inthe pating luster beteween each plating lots.

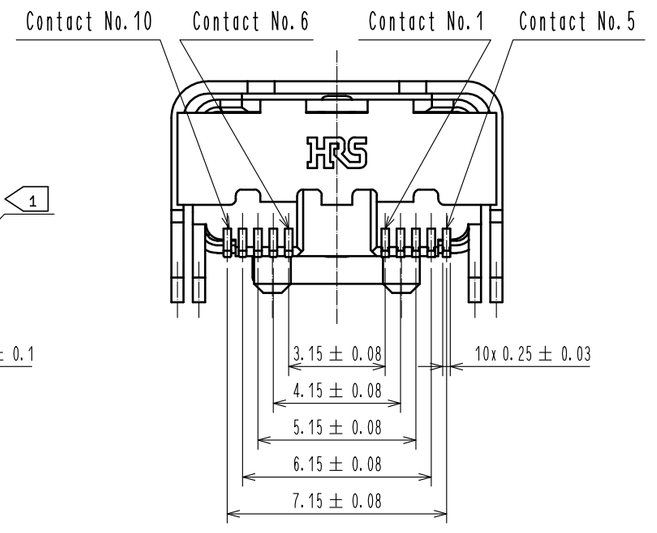
3 Per reel : 550 pcs.

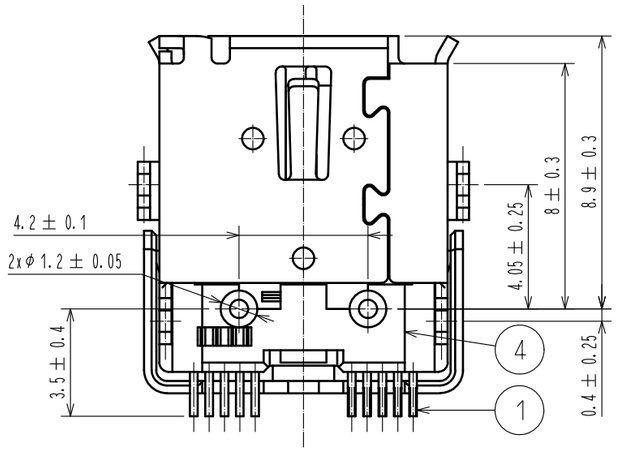
4 Refer to the mated condition diagram for the panel thickness and layout.

5. This produt is mounted by reflow soldering.
Refer to specification sheet ELC-129411-00-00 for reflow soldering.

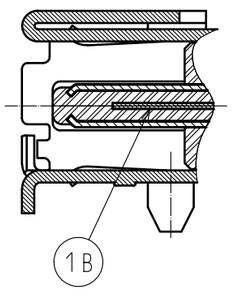








A-A



NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
3	Stainless Steel		7	PE	
2	LCP	Gray、UL94V-0	6	PS	
1	Copper Alloy	Contact area : Gold 0.2 μm min. Lead area : Gold 0.03 μm min. Under plating : Nickel 2 μm min.	5	Stainless Steel	Surface : Tin 1 μm min. Under plating : Nickel 0.2 μm min.
			4	LCP	Gray、UL94V-0

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	5 : 1	0				

HIROSE ELECTRIC CO., LTD.

APPROVED	RI. TAKAYASU	18.09.13
CHECKED	RI. TAKAYASU	18.09.13
DESIGNED	TS. SAKAIZAWA	18.09.13
DRAWN	TS. SAKAIZAWA	18.09.13

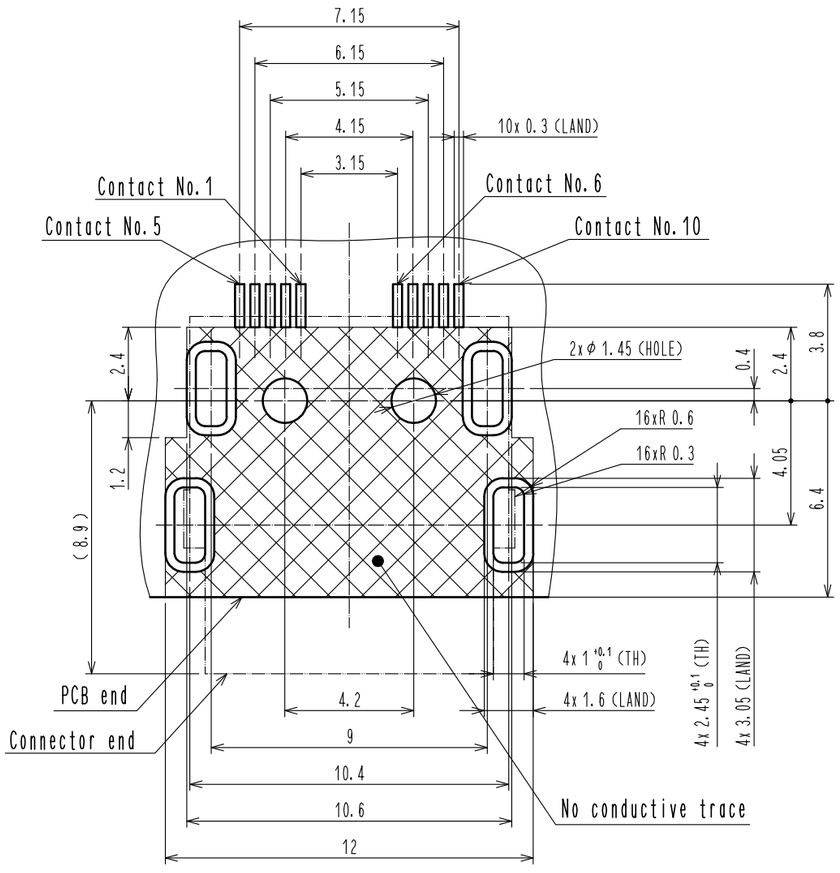
DRAWING NO.	EDC-129411-00-00
PART NO.	IX60G-B-10P
CODE NO.	CL251-0017-0-00

0 1/3

RoHS2 (10 substances conformity)

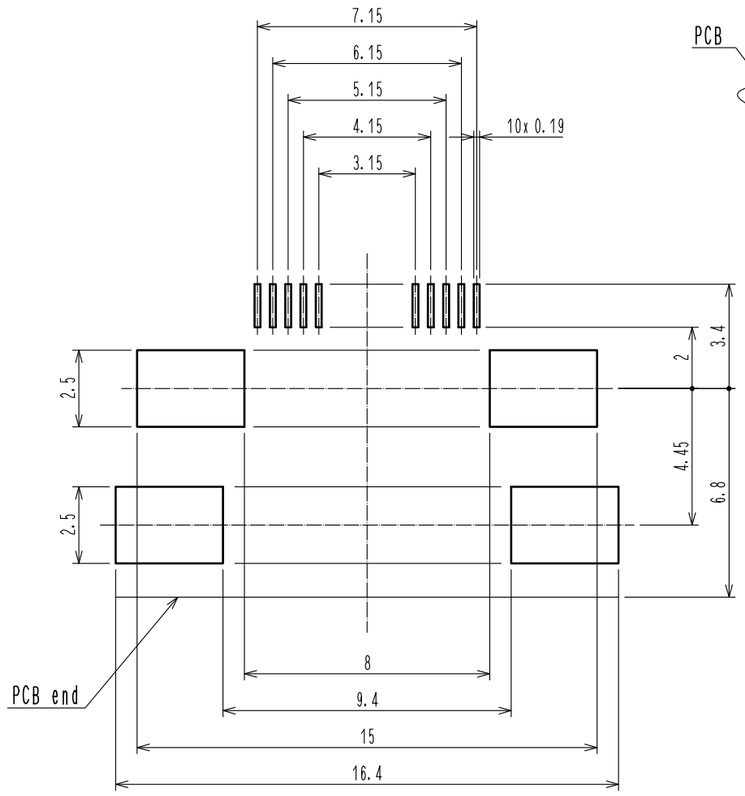
2019/06/17 17:56:04 TS.SAKAIZAWA

Reference PCB Layout (Connector Mounting Side) (t = 1.6)



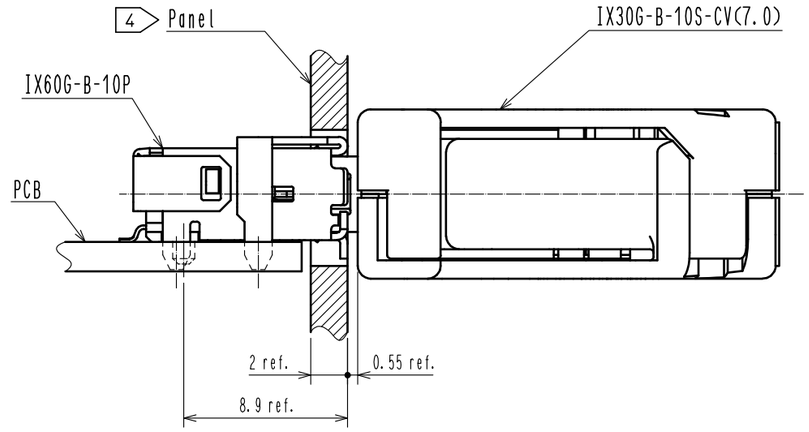
General tolerance is +/- 0.05

6 Reference Metal Mask Layout (t = 0.15)

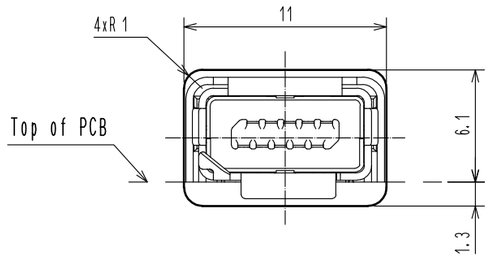


General tolerance is +/- 0.02

Mated Condition (Free)



4 Reference Dimensions of Panel Cutout (Free)



Dimension is reference.

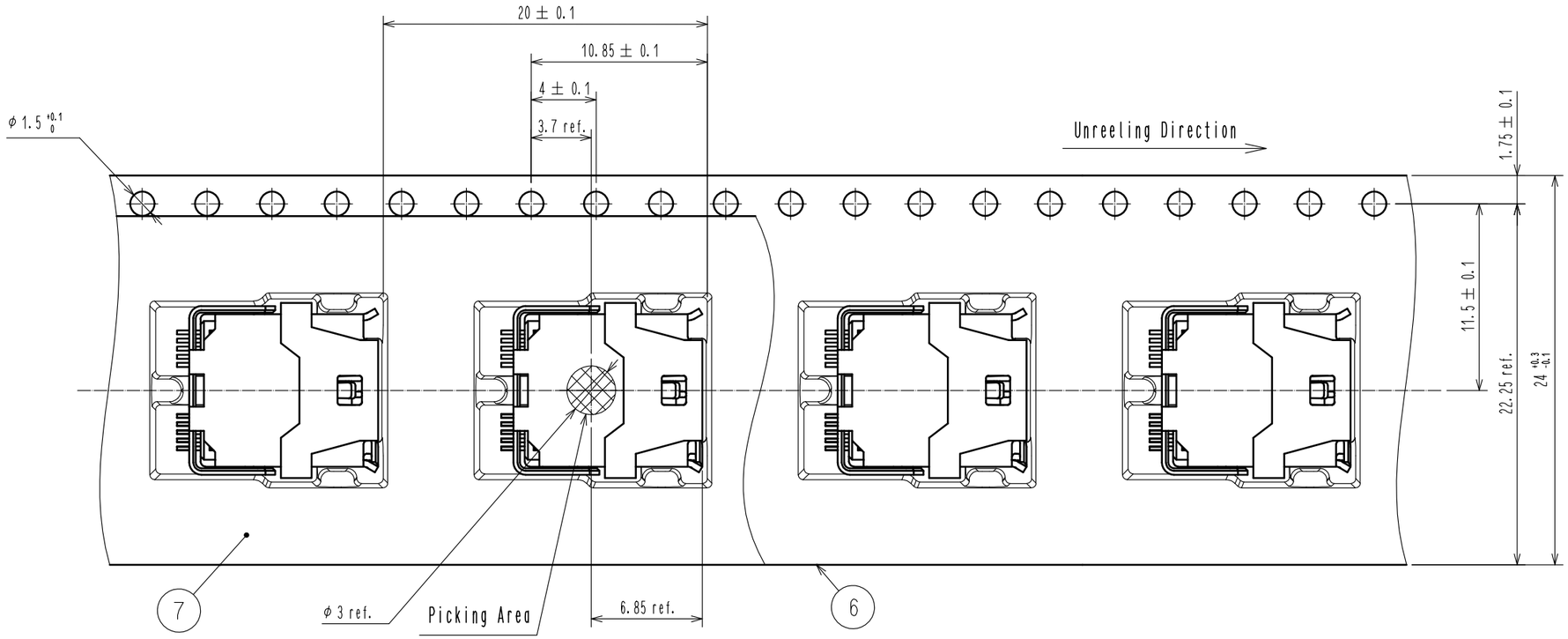
6 Thickness of metal mask is 0.1 mm min.
Metal mask dimensions of the drawings described, are reference dimensions for 0.15 mm thickness metal mask.
Change the metal mask dimensions by thickness of the metal mask, thickness of PCB, component of solder paste and mounting conditions.
Change the metal mask dimensions in case of mounting IX60G-*-10P in parallel.
Change the metal mask dimensions, if there are other mounting parts or implementation pattern around the portion of mounting position of IX60G-*-10P.
Refer to the technical specification (ETAD-E3170-00) for different variations of the metal mask pattern width.

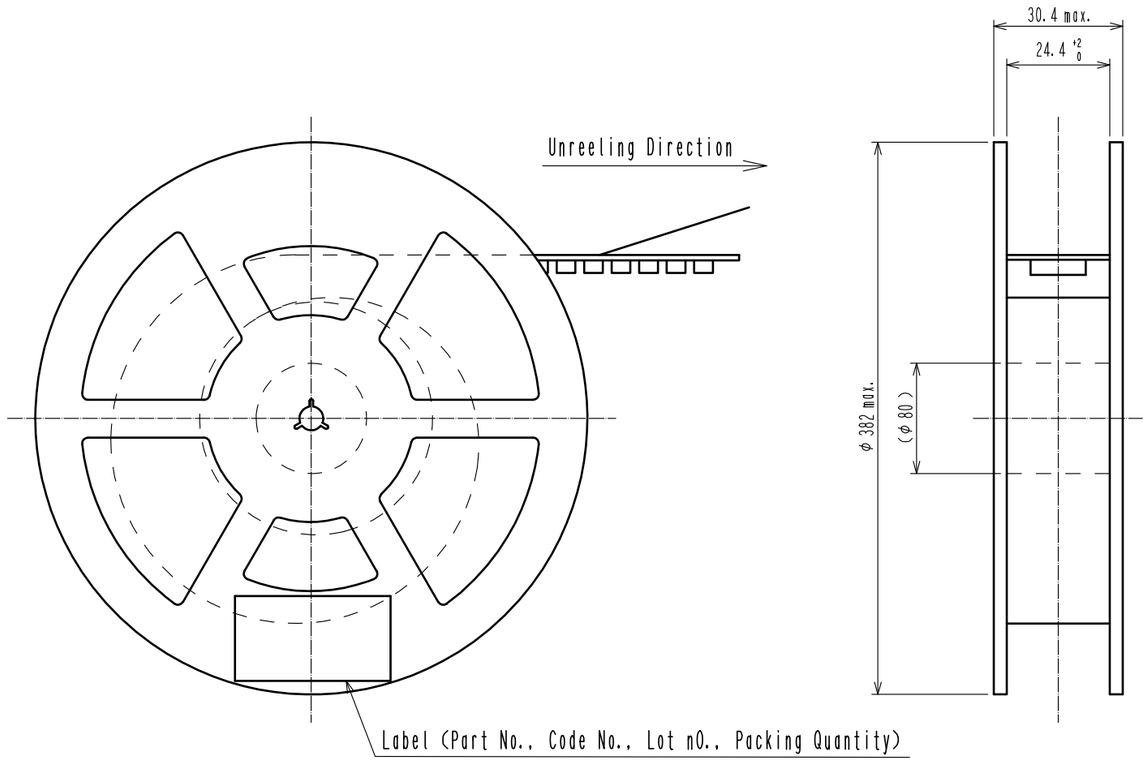
DRAWING NO.	EDC-129411-00-00
PART NO.	IX60G-B-10P
CODE NO.	CL251-0017-0-00

RoHS2 (10 substances conformity)

2019/06/17 17:56:04 TS.SAKAIZAWA

3 Drawing for packing (Free)

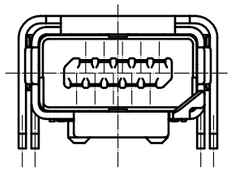




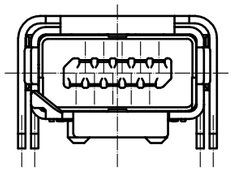
NOTES 7. This product (Type B) is used for non Ethernet applications
like signaling, serial or other industrial bus communication systems.
Please use Type A for 10/100Mbit/s and 1/10 Gbit/s Ethernet communication.

Mating Shape

Type A



Type B



DRAWING NO.	EDC-129411-00-00
PART NO.	IX60G-B-10P
CODE NO.	CL251-0017-0-00

△0 3/3

RoHS2 (10 substances conformity)